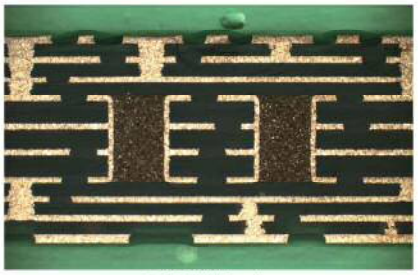
HDI PCB PPBU®

Laser via build-up multi layer PCB

Automotive

Example



3-4-3 BVH Stack

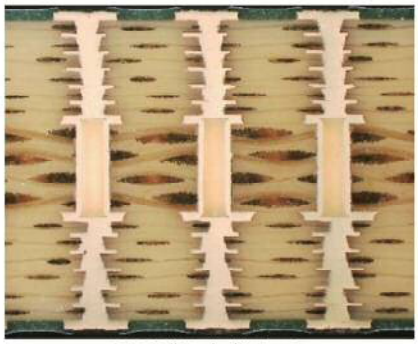
Roadmap（ECU、ADAS、自動運転）

Unit : μm

	2024	2025	2026	2027
BGA Pitch	0.5mm(Pin1)	←	0.40mm(Pin0)	0.40mm(Pin1)
Structure	BVH Stack ～14L ～4Stack t=～1.6mm	←	Full Stack ～14L ～4Stack t=～1.6mm	Full Stack ～12L ～5Stack t=～1.6mm
L／S	75/75(Inner) 75/75(Outer)	←	60/60(Inner) 60/60(Outer)	50/50(Inner) 50/50(Outer)
Land/LVH	250/100	←	200/100	200/100
Land/IVH	450/200	←	350/150	350/150
Land/TH	450/200	←	350/150	350/150

Communication base station Data center

Example



6-2-6 Full Stacked(1.6mmt)
0.4 ㎜ Pitch　1800pin

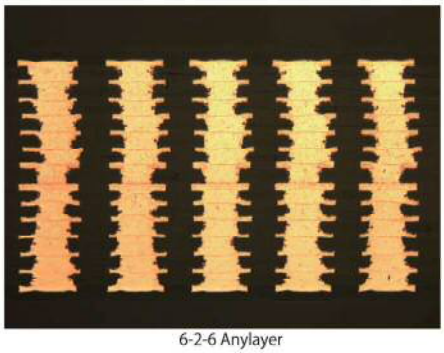
Specification

Unit : μm

	2024
L／S	50/50(Inner) 75/75(Outer)
Land/LVH	250/100
Land/IVH	300/150
Land/TH	300/600
Z0 Zdiff	±10%

Mobile

Example



6-2-6 Anylayer

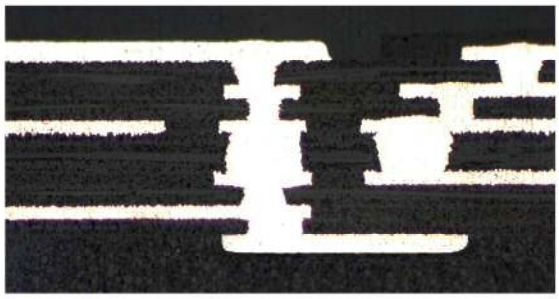
Roadmap

Unit:μm

Year			2025-26	2027	2028	2029
BGA Pitch	Pin to Pin		250 350(Pin2)	250 350(Pin2)	250 350(Pin2)	250 350(Pin2)
Thickness	total	10L	510	470	470	470
		12L	600	550	550	550
		14L	700	640	640	640
L/S	MSAP		N/A	N/A	30/30	25/25
	Subtractive		30/40	30/40	30/40	30/40
LVH/Land	Bu	Hole dia.	60	60	60	60
		Land dia.	150	150	150	150
	Core	Hole dia.	80	80	80	80
		Land dia.	200	200	200	200

Module R&D

Example



2-2-2 Anylayer (0.22mmt)

Roadmap

Unit:μm

Year			2025-26	2027	2028	2029	2030	2031
CSP Pitch	Pin to Pin		200	170	150 170(Pin1)	125	115	110
Thickness	total	4L	200	160	160	150	145	145
		6L	300	220	220	200	195	195
		8L	390	280	280	250	245	245
L/S	MSAP		30/30 Advanced	25/25 Advanced	25/25 Mass Pro	20/25 Mass Pro	20/25 Mass Pro	20/20 Mass Pro
	Subtractive		30/40	30/40	25/40	20/40	20/40	20/40
LVH/Land	Bu	Hole dia.	60	50	50	50	35	35
		Land dia.	110	90	90	90	80	70
	Core	Hole dia.	80	80	80	60	60	60
		Land dia.	120	110	110	110	110	110

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